



SOT2X

Small Outline Transistor Package (SOT2X)

DESCRIPTION

Lingsen's 3L, 5L and 6L lead SOT packages are lead frame based plastic encapsulated package offering gull wing lead, SMT performance characteristics and ideal for customers' low-cost packaging solution. Lingsen is one of the largest providers of SOT 2X series in the world.

The package meets JEDEC Moisture Sensitivity Level 3 standard that ensures reliability in its functions.

SPECIFICATIONS

- Die Thickness 330um (13mils) maximum
- Gold Wire 99.99% Au
- Mold Compound EME G600 (Green)
EME 6300H (Non-Green)
- Plating NiPdAu (PPF) / Matte Tin
- Marking Laser Mark
- Packing Tape & Reel / Shielding Bag

APPLICATIONS

- Wireless / RF
- Analog devices
- Ultra thin hand-held portable products such as cellular phones, data storage systems, notebook computers and pagers

RELIABILITY

- MSL Level: MSL 3 @ 240°C for Sn/Pb
- MSL Level: MSL 3 @ 260°C for Pb-Free & Green
- Pressure Cook Test: 168hrs (121°C, 100%RH, 2atm)
- Temperature Cycling: 500cycles (-65°C/+150°C)
- HAST: 100hrs (130°C, 85%RH)
- Temperature & Humidity Test: 1,000hrs (85°C, 85%RH)
- High Temperature Storage: 1,000hrs (150°C)

FEATURES

- Available pin count 3L, 5L & 6L
- Lead pitch 0.95mm
- JEDEC MSL level 3 qualified for all pin counts

PACKAGE AVAILABILITY

Package	Body Size (mm)	Pad Size (mm)	Die Size (mm)	Thermal Performance θ_{ja} (°C/W)
SOT-23	2.9x1.6	1.2x1.2	0.9398x1.0414	147.82
SOT-26	2.9x1.6	1.5x1.2	1.28x0.775	130.69

Note: Simulated with JEDEC Standard 4-layer test board under still air condition, ambient temperature 45°C

ELECTRICAL PERFORMANCE

Package	Body Size (mm)	Pad Size (mm)	Frequency (MHz)	Self Inductance (nH)	Self Capacitance (pF)	Resistance (mohm)
SOT-23	2.9x1.6	1x1	100	0.877~1.159	0.216~0.498	61.22~74.7
SOT-26	2.9x1.6	1.5x1.2	100	0.718~1.034	0.213~0.646	34.06~72.3

Note: Results are simulated. Data is available through 2.5GHz.

CROSS-SECTION

